

FIG 1

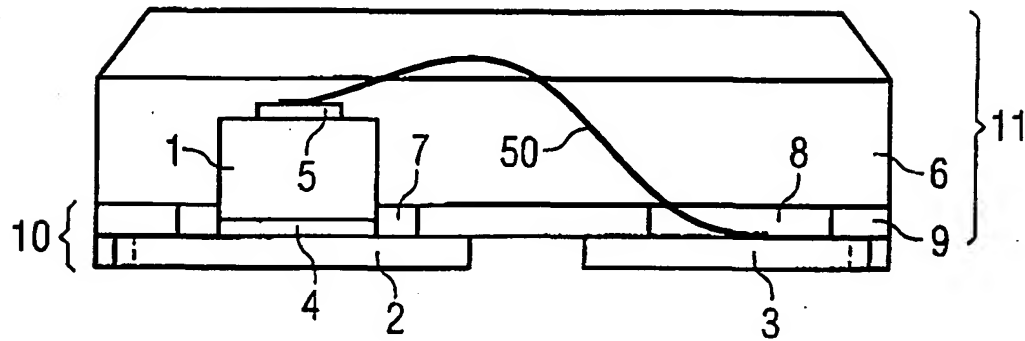


FIG 2

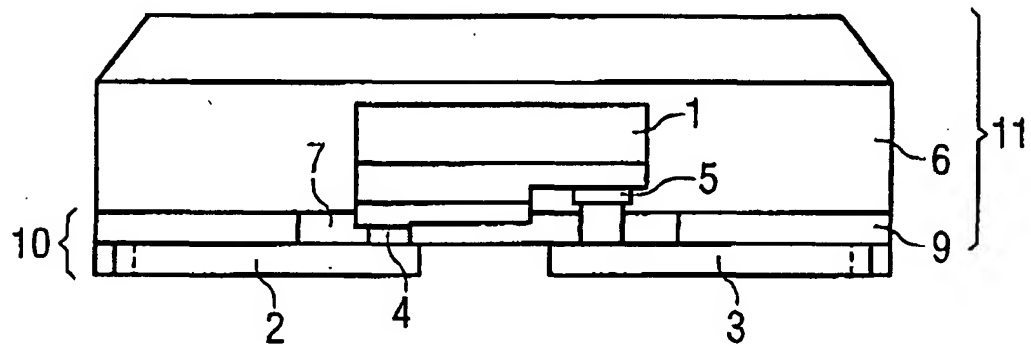


FIG 3A



FIG 3B

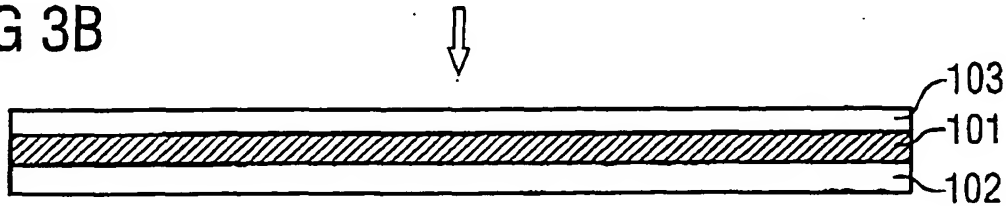


FIG 3C

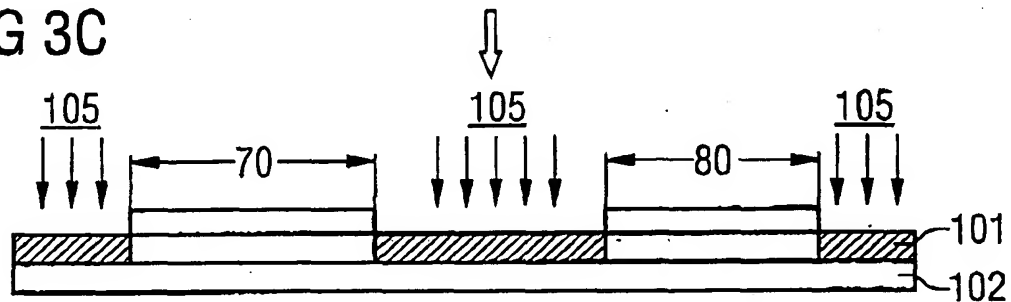


FIG 3D

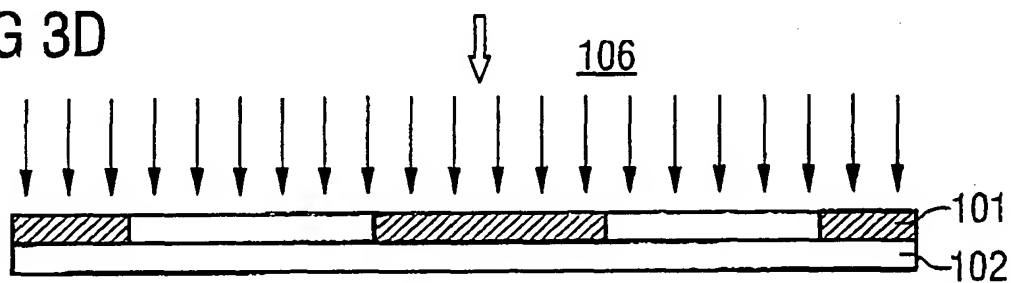


FIG 3E

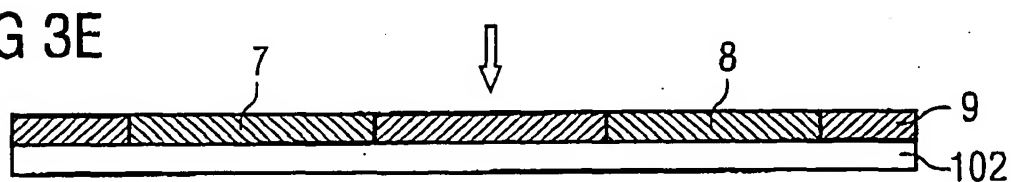


FIG 3F

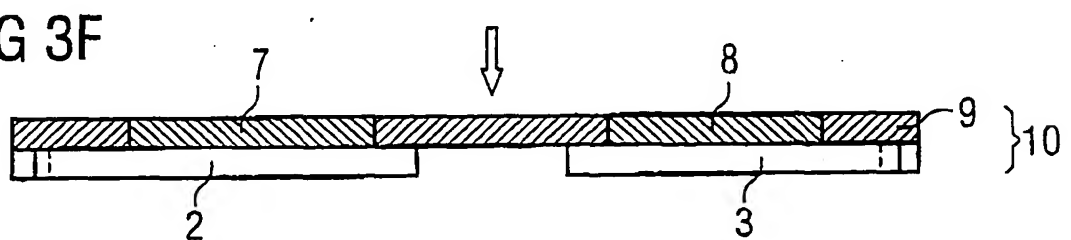


FIG. 4A

A cross-sectional view of a substrate 101 with a thin layer 102 on its top surface. The substrate 101 is represented by a hatched rectangular block. The thin layer 102 is a narrow, white rectangular strip positioned on the top horizontal surface of the substrate 101. Reference numerals 101 and 102 are located to the right of the substrate and layer, respectively, with leader lines pointing to them.

FIG 4B

FIG 4B illustrates a device with two pressure points. The top part shows two views of a rectangular component 104. The left view shows a pressure point 105 with a width of 70. The right view shows a pressure point 105 with a width of 80. The bottom part shows a cross-section of the device with layers 101 and 102, and shaded regions corresponding to the pressure points.

FIG 4C

106

101

102

FIG 4D

A cross-sectional view of a device. A substrate 102 is shown at the bottom. A layer 9 is disposed on top of the substrate 102. The layer 9 is divided into regions 7 and 8 by vertical dividers. A downward arrow is positioned above the center of the structure.

FIG 4E

FIG 4E is a cross-sectional view of a device 10. The device consists of a substrate with two rectangular regions 2 and 3. A layer 7 is deposited on region 2, and a layer 8 is deposited on region 3. A thin layer 9 covers the top of the entire structure. A downward arrow indicates a force or pressure applied to the top surface.

FIG 5A

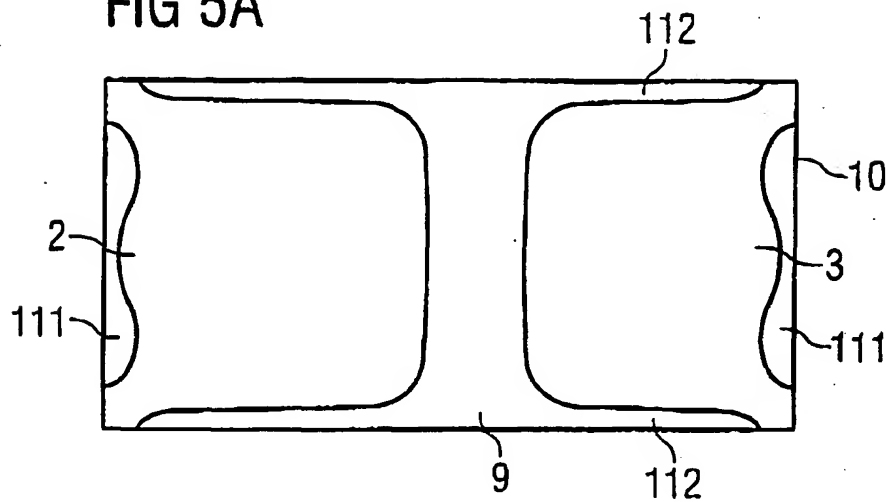
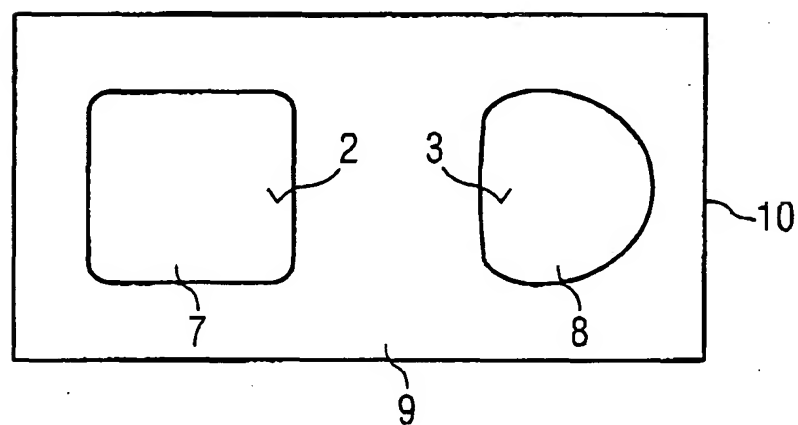


FIG 5B



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FIG 6B

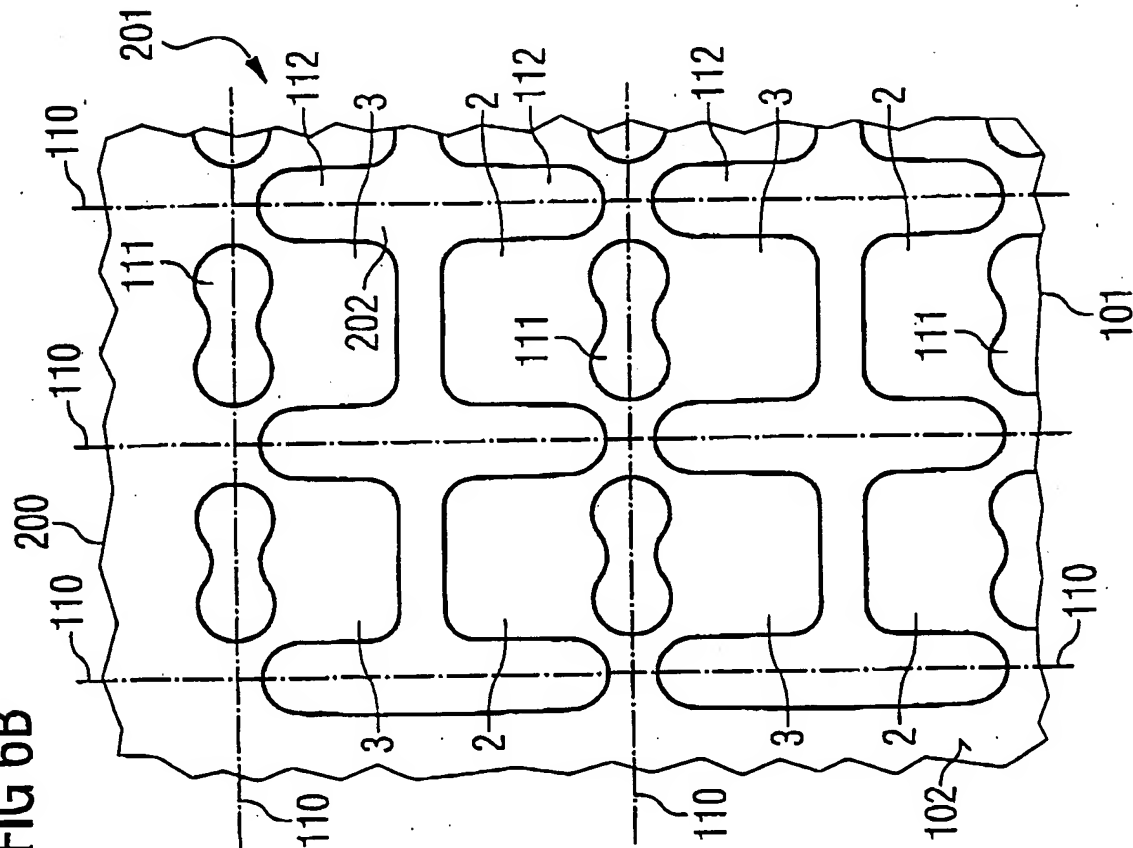


FIG 6A

